Product/Process Change Notice - PCN 13_0207 Rev. A

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

PCN Title: Assembly Transfer of Select 3x3mm LFCSP Products Amkor Philippines

Publication Date: 12-Jul-2014

Effectivity Date: 12-Jul-2014 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

To include completed Qualification Results Summary

Description Of Change

ADI is transferring to subcontractor Amkor Philippines for the assembly of select 3x3 LFCSP products.

The package outline dimensions, wire diameter and die attach epoxy of each product will be maintained. The mold compound is changing from Sumitomo G770 to Sumitomo G700. See BOM attachment for details.

Reason For Change

ADI is transferring to Amkor Philippines due to the closure of STATS ChipPAC Malaysia at the end of 2014.

ADI's assembly subcontractors manufacture products using Analog Devices specified manufacturing flows, materials, process controls and monitors, ensuring the same level of quality and reliability on products they receive from the new site.

Impact of the change (positive or negative) on fit, form, function & reliability

The transfer will have no impact on the form, fit, function and reliability of the devices.

Product Identification *(this section will describe how to identify the changed material)*

The parts that will be assembled after the transfer will be identified by assembly lot and the country of origin.

Summary of Supporting Information

Qualification has been performed per AEC-Q100, Stress Test Qualification for Integrated Circuits. See attached Qualification Results Summary.

Supporting Documents

Attachment 1: Type: Qualification Results Summary

ADI_PCN_13_0207_Rev_A_Qualification Results Summary.pdf

Attachment 2: Type: Detailed Change Description

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative					
Americas:	PCN_Americas@analog.com	**Europe:**	PCN_Europe@analog.com	**Japan:**	PCN_Japan@analog.com
				Rest of Asia:	PCN_ROA@analog.com

Appendix A - Affected ADI Models				
Existing Parts - Product Family / Model Number (4)				
ADA4830-1 / ADA4830-1BCPZ-R7	ADA4830-1 / ADA4830-1WBCPZ-R7	ADA4830-2 / ADA4830-2BCPZ-R7	ADA4830-2 / ADA4830-2WBCPZ-R7	

Appendix B - Revision History			
Rev	**Publish Date**	**Effectivity Date**	**Rev Description**
Rev. -	25-Nov-2013	15-Apr-2014	Initial Release
Rev. A	12-Jul-2014	12-Jul-2014	To include completed Qualification Results Summary

Automotive Qualification Results Summary of Sawn LFCSP Package at Amkor Philippines(ATP)

QUALIFICATION RESULTS

Test	Conditions	Sample Size	RESULTS
Temperature/Humidity/Bias (THB)*	JEDEC *JESD22-A101*	**3 x 77**	Passed
Temperature Cycle (TC)*	JEDEC *JESD22-A104*	**3 x 77**	Passed
Autoclave (AC)*	JEDEC *JESD22-A102*	**3 x 77**	Passed
Solder Heat Resistance (SHR)*	JEDEC/IPC *J-STD-020*	**3 x 11**	Passed
High Temperature Storage Life (HTSL)	JEDEC *JESD22-A103*	**1 x 77**	Passed
Field Induced Charged Device Model (FICDM)	JEDEC *JESD22-C101*	**1 x 18**	Passed

*These samples will be subjected to preconditioning (per J-STD-020 Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following: Bake: 24 hrs @ 125ºC, Soak: Unbiased Soak: 192 hrs @ 30ºC, 60%RH, Reflow: 3 passes through an oven with a peak temperature of 260ºC. TCT samples will be wire-pull test after 500 cycles. Preconditioned per JEDEC/IPC J-STD-020.